

CLAIM AMENDMENTS:

Please cancel Claims 36 and 66, amend Claims 55 and 56, and add new Claims 68-70, as follows.

1.-22. (Cancelled)

23. (Previously Presented) The imaging apparatus according to Claim 55, wherein the wavelength converting member comprises a fluorescent member.

24. (Previously Presented) The imaging apparatus according to Claim 55, wherein the conductive member comprises an insulating base and a conductive layer provided thereon.

25. (Previously Presented) The imaging apparatus according to Claim 55, wherein the conductive member comprises a metal.

26. (Previously Presented) The imaging apparatus according to Claim 25, wherein the metal comprises aluminum.

27. (Cancelled)

28. (Previously Presented) The imaging apparatus according to Claim 55, wherein an area of the conductive member overlaps said photoelectric conversion elements.

29. (Previously Presented) The imaging apparatus according to Claim 55, wherein a periphery of the conductive member is sealed.

30. (Previously Presented) The imaging apparatus according to Claim 55, wherein a periphery of the conductive member extends over the outer edges of the and an edge portion of said conductive member is sealed so as to cover the outer edges of the plurality of substrates.

31. (Previously Presented) The imaging apparatus according to Claim 30, wherein a space is formed between the outer edges of said plurality of substrates and the conductive member.

32. (Cancelled)

33. (Cancelled)

34. (Previously Presented) The imaging apparatus according to Claim 55, wherein the resin is provided so as to cover a peripheral portion of said plurality of substrates and all end faces of the conductive member.

35. (Previously Presented) The imaging apparatus according to Claim 55, wherein the plurality of photoelectric conversion elements are arranged in a matrix.

36. - 54. (Cancelled)

55. (Currently Amended) An imaging apparatus comprising:

a photoelectric conversion device having a plurality of substrates each having a plurality of photoelectric conversion elements and lead electrode portions on a principal surface thereof, the plurality of substrates being arranged adjacent each other in a plane, and a wavelength converting member arranged on the photoelectric conversion elements over the plurality of substrates;

a control circuit connected to said lead electrode portions, for driving the device;

a housing for said photoelectric device and said control circuit;

a grounded conductive member disposed within said housing and ~~on~~ fixed to said wavelength converting member; and

a resin that seals at least a portion of said principal surface of each said substrate and at least a part of an end face of the conductive member and at least a part of each lead electrode portion, wherein said plurality of substrates and the conductive member are in close proximity with each other.

56. (Currently Amended) An imaging apparatus comprising:

a photoelectric conversion device having a plurality of photoelectric conversion elements and lead electrode portions on a surface of a panel;

a wavelength converting member arranged on the photoelectric conversion elements;

a grounded conductive member arranged on and fixed to the wavelength converting member; and

a resin that seals at least a portion of the surface of the panel and at least a part of an end face of the conductive member and at least a part of each said lead electrode portion, wherein the surface of the panel and the conductive member are in close proximity with each other.

57. (Previously Presented) The imaging apparatus according to Claim 56, wherein the wavelength converting member comprises a fluorescent member.

58. (Previously Presented) The imaging apparatus according to Claim 56, wherein the conductive member comprises a metal.

59. (Previously Presented) The imaging apparatus according to Claim 58, wherein the metal comprises aluminum.

60. (Previously Presented) The imaging apparatus according to Claim 56, wherein an area of the conductive member overlaps said photoelectric conversion elements.

61. (Previously Presented) The imaging apparatus according to Claim 56, wherein a periphery of the conductive member is sealed.

62. (Previously Presented) The imaging apparatus according to Claim 56, wherein a periphery of the conductive member extends over the outer edges of the panel and an edge portion of said conductive member is sealed so as to cover the outer edges of the panel.

63. (Previously Presented) The imaging apparatus according to Claim 62, wherein a space is formed between the outer edge of the panel and the conductive member.

64. (Previously Presented) The imaging apparatus according to claim 56, wherein the resin is provided so as to cover a peripheral portion of the panel and all the end faces of the conductive member.

65. (Previously Presented) The imaging apparatus according to Claim 56, wherein the plurality of photoelectric conversion elements are arranged in a matrix.

66. (Cancelled)

67. (Previously Presented) The imaging apparatus according to Claim 58, wherein the panel comprises a plurality of substrates arranged adjacent each other in a plane.

68. (New) The imaging apparatus according to Claim 55, wherein the conductive member is fixed to said wavelength converting member so as to cover one surface and an end face of said wavelength converting member.

69. (New) The image apparatus according to Claim 56, wherein the conductive member is fixed to said wavelength converting member so as to cover one surface and an end face of said wavelength converting member.

70. (New) A photoelectric conversion device comprising:
a plurality of photoelectric conversion elements arranged two-dimensionally on a substrate;
a wavelength converting member arranged on the plurality of photoelectric conversion elements; and
a conductive member arranged on the wavelength converting member for serving as a shielding member;
wherein the conductive member covers a wider area than an area in which the plurality of photoelectric conversion elements are arranged two-dimensionally and has a connector for grounding, and wherein said conductive member is fixed to the wavelength converting member.